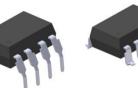
DATASHEET

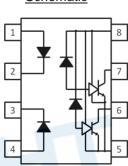
8 PIN DIP HIGH SPEED 10MBit/s LOGIC GATE **PHOTOCOUPLER EL263X** series





Features

- High speed 10Mbit/s
- 10kV/µs min. common mode transient immunity (EL2631)
- Guaranteed performance from -40 to 85°C
- · Logic gate output
- High isolation voltage between input and output (Viso=5000 Vrms)
- Pb free and RoHS compliant.
- UL and cUL approved(No. E214129)
- VDE approved (No. 132249)
- SEMKO approved
- NEMKO approved
- DEMKO approved
- FIMKO approved



A 0.1µF bypass capacitor must be connected between pins 8 and 5 *3

Pin Configuration

- 1. Anode
- 2. Cathode
- 3. Cathode
- 4. Anode
- 5. Gnd
- 6. Vout 2 7. Vout 1
- 8. Vcc

Description

The EL2630 and EL2631 are consists of an infrared emitting diode optically coupled to a high speed integrated photo detector logic gate with a strobable output. It is packaged in a 8-pin DIP package and available in wide-lead spacing and SMD options.

Applications

- Ground loop elimination
- LSTTL to TTL, LSTTL or 5 volt CMOS
- · Line receiver, data transmission
- Data multiplexing
- Switching power supplies
- Pulse transformer replacement
- Computer peripheral interface
- High speed logic ground isolation

Truth Table (Positive Logic)

Input	Output		
Н	L		
L	Н		

Schematic

Absolute Maximum Ratings (T_A=25°C)

	Parameter	Symbol	Rating	Unit
	Forward current	l _F	20	mA
Input	Reverse voltage	V _R	5	V
	Power dissipation	Po	40	mW
	Power dissipation	Pc	60	mW
	Output current	lo	50	mA
Output	Output voltage	Vo	7.0	V
	Supply voltage	Vcc	7.0	V
Output Po	ower Dissipation	Po	85	mW
Isolation v	voltage *1	V _{ISO}	5000	Vrms
Operating temperature		T _{OPR}	-40~+100	°C
Storage te	emperature	T _{STG}	-55~+125	°C
Soldering	temperature *2	T _{SOL}	260	°C

Notes:

*1 AC for 1 minute, R.H.= 40 ~ 60% R.H. In this test, pins 1, 2, 3 & 4 are shorted together, and pins 5, 6, 7 & 8 are shorted together.

*2 For 10 seconds.

Electrical Characteristics (T_A =-40 to 85°C unless specified otherwise)

Parameter	Symbol	Min.	Typ.*	Max.	Unit	Condition
Forward voltage	V _F	-	1.4	1.8	V	I _F = 10mA, T _A =25°C
Reverse voltage	V _R	5.0	-	-	V	I _R = 10μΑ
Temperature coefficient of forward voltage	$\Delta V_F / \Delta T_A$	-	-1.8	-	mV/°C	I _F =10mA
Input capacitance	CIN	-	60	-	pF	V _F =0, f=1MHz
Output Parameter	Symbol	Min	Тур.*	Max.	Unit	Condition
High level supply current	Іссн	-	12.5	18	mA	I _F =0mA, V _{CC} =5.5V
Low level supply current	Iccl	-	14.5	21	mA	I _F =10mA, V _{CC} =5.5V

Transfer Characteristics (T_A =-40 to 85°C unless specified otherwise)

Parameter	Symbol	Min	Тур.	Max.	Unit	Condition
HIGH Level Output Current	Іон		2.1	100	μA	V _{CC} =5.5V, V _O =5.5V, I _F =250µA
LOW Level Output Current	Vol	-	0.35	0.6	V	$V_{CC} = 5.5V$, I _F =5mA, I _{CL} =13mA
Input Threshold Current	IFT	-	2.5	5	mA	V_{CC} = 5.5V, V_{O} =0.6V, I_{OL} =13mA

Switching Characteristics (T_A =-40 to 85°C, V_{CC}=5V, I_F=7.5mA unless specified otherwise)

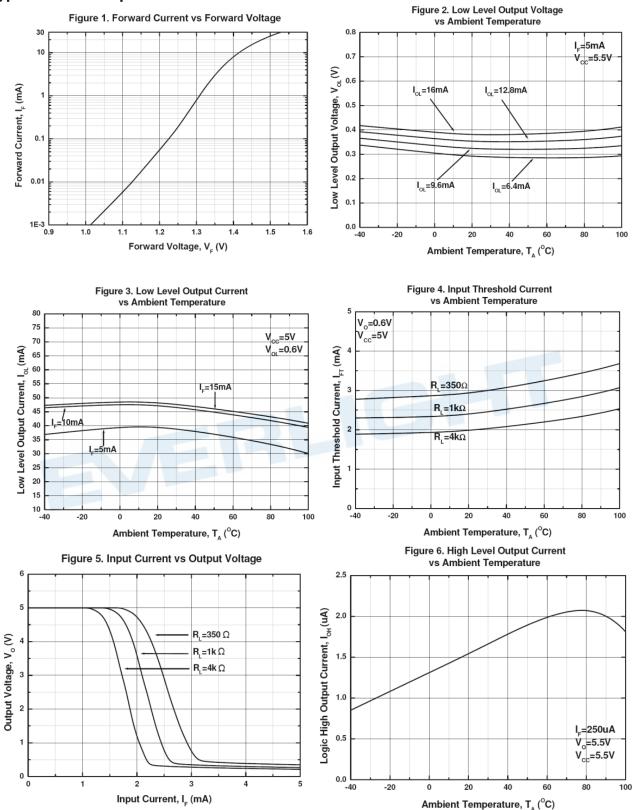
Parameter	Symbol	Min	Тур.	Max.	Unit	Condition
Propagation delay time to output High level* ⁴ (Fig.12)	T _{PLH}	-	35	100	ns	C_L = 15pF, R_L =350 Ω , T_A =25°C
Propagation delay time to output Low level* ⁵ (Fig.12)	T _{PHL}	-	40	100	ns	C_L = 15pF, R_L =350 Ω , T_A =25°C
Pulse width distortion	T _{PHL} -T _{PLH}	-	5	35	ns	$C_L = 15 pF, R_L = 350 \Omega$
Output rise time* ⁶ (Fig.12)	tr	-	40	-	ns	$C_L = 15 pF, R_L = 350 \Omega$
Output fall time* ⁷ (Fig.12)	t _f	-	10	-	ns	C_L = 15pF, R_L =350 Ω

Switching Characteristics (T_A =-40 to 85°C, V_{CC}=5V, I_F=7.5mA unless specified otherwise)

Parameter		Symbol	Min	Тур.	Max.	Unit	Condition
Common Mode Transient Immunity at Logic High ^{*8}	EL2630	- CM _H	5,000	-	-	- V/µS	$ I_{F} = 0mA, V_{CM} = 1KV_{P-P}, \\ V_{OH} = 2.0V, R_{L} = 350\Omega, \\ T_{A} = 25^{\circ}C(Fig.13) $
	EL2631		10,000	20,000	-		$ I_{F} = 0mA , V_{CM} = 1KV_{P-P}, \\ V_{OH} = 2.0V, R_{L} = 350\Omega, \\ T_{A} = 25^{\circ}C(Fig.13) $
Common Mode Transient Immunity at Logic Low ^{*9}	EL2630	- CM∟	5,000	-	-	V/µS	$I_{F} = 7.5 \text{mA}, V_{CM} = 1 \text{KV}_{\text{p-p}}, \\ V_{OL} = 0.8 \text{V}, \text{R}_{L} = 350 \Omega, \\ T_{\text{A}} = 25^{\circ} \text{C}(\text{Fig.13})$
	EL2631		10,000	20,000	-		$I_{F} = 7.5 \text{mA}, V_{CM} = 1 \text{KV}_{\text{p-p}}, \\ V_{OL} = 0.8 \text{V}, \text{R}_{L} = 350 \Omega, \\ T_{A} = 25^{\circ} \text{C}(\text{Fig.13})$







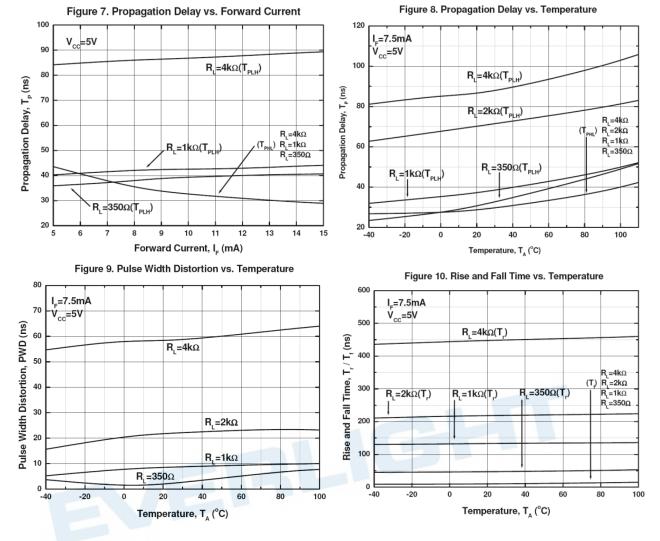
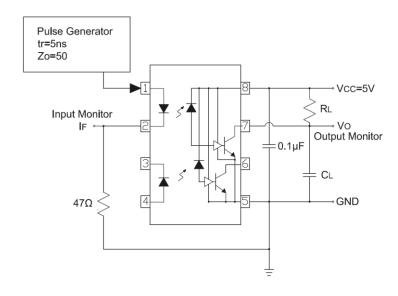
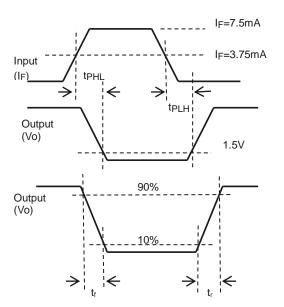


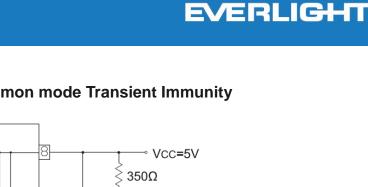
Fig. 11 Test circuit and waveforms for tPHL, tPLH, tr, and tf



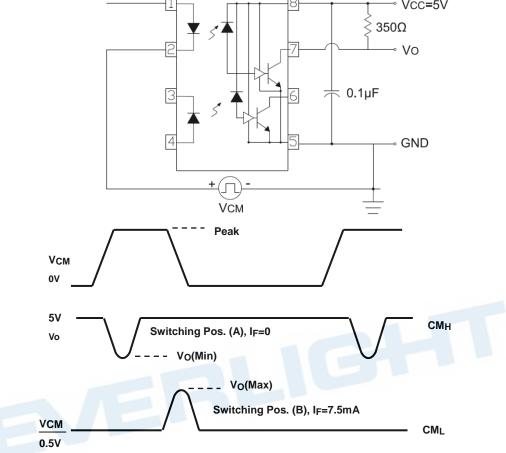
6



IF







Note

- *3 The VCC supply must be bypassed by a 0.1µF capacitor or larger. This can be either a ceramic or solid tantalum capacitor with good high frequency characteristic and should be connected as close as possible to the package VCC and GND pins
- *4. tPLH Propagation delay is measured from the 3.75mA level on the HIGH to LOW transition of the input current pulse to the 1.5 V level on the LOW to HIGH transition of the output voltage pulse.
- *5. tPHL Propagation delay is measured from the 3.75mA level on the LOW to HIGH transition of the input current pulse to the 1.5 V level on the HIGH to LOW transition of the output voltage pulse.
- *6. tr Rise time is measured from the 90% to the 10% levels on the LOW to HIGH transition of the output pulse.
- *7. tf Fall time is measured from the 10% to the 90% levels on the HIGH to LOW transition of the output pulse.
- *8 CMH– The maximum tolerable rate of rise of the common mode voltage to ensure the output will remain in the HIGH state (i.e., VOUT > 2.0V).
- *9 CML- The maximum tolerable rate of rise of the common mode voltage to ensure the output will remain in the LOW output state (i.e., VOUT < 0.8V).



Order Information

Part Number

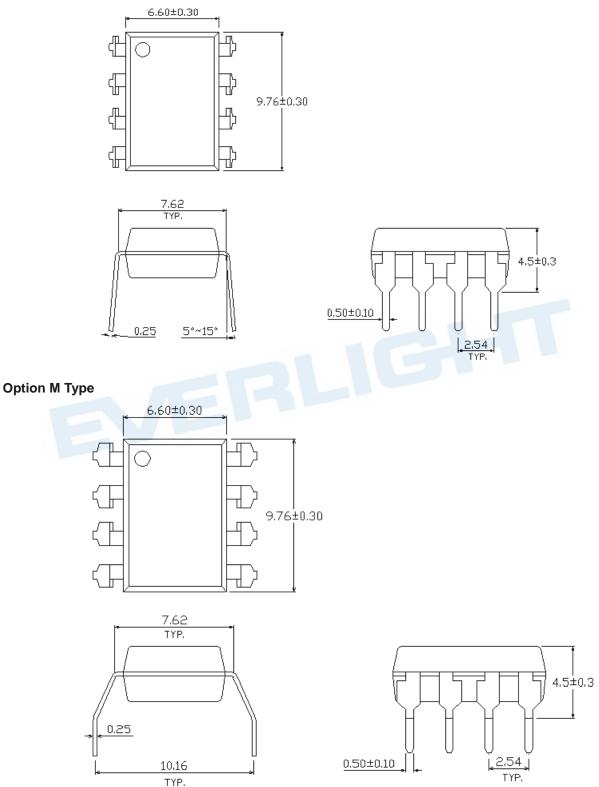
EL263XY(Z)-V

Note

- X = (0 or 1) for EL26 part no.
- Y = Lead form option (S, S1, M or none)
- Z = Tape and reel option (TA, TB or none).
- V = VDE (optional)

Package Dimension (Dimensions in mm)

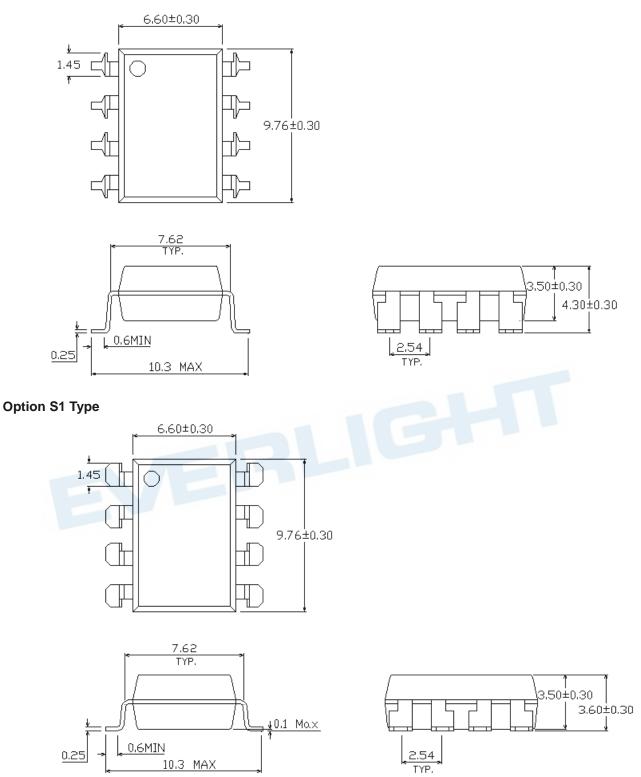
Standard DIP Type



DATASHEET 8 PIN DIP HIGH SPEED 10MBit/s LOGIC GATE PHOTOCOUPLER EL263X series

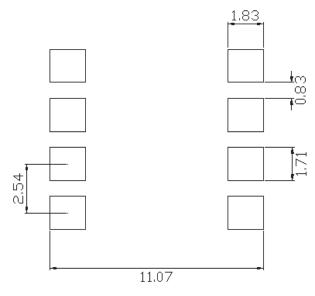


Option S Type





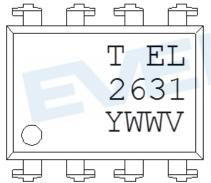
Recommended pad layout for surface mount leadform



Notes.

Suggested pad dimension is just for reference only. Please modify the pad dimension based on individual need. GHT

Device Marking

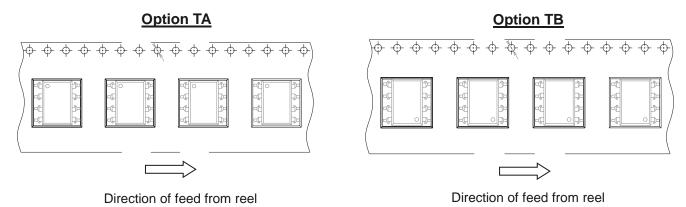


Notes

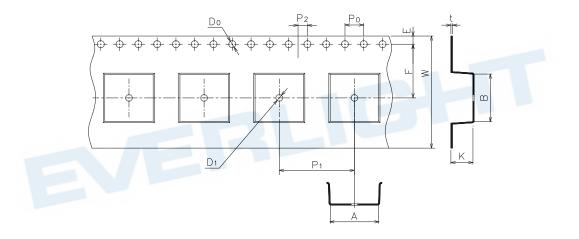
Т	denotes Factory
	No code : made in China
	T : made in Taiwan
EL	denotes EVERLIGHT
2631	denotes Device Number
Υ	denotes 1 digit Year code
WW	denotes 2 digit Week code
V	denotes VDE (optional)



Tape & Reel Packing Specifications



Tape dimension



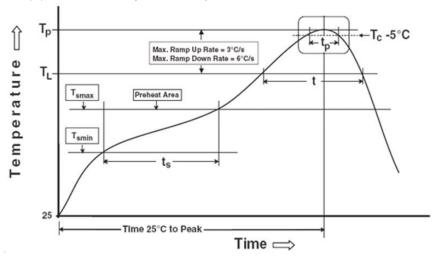
Dimension No.	А	В	Do	D1	E	F
Dimension(mm)	10.4±0.1	10.0±0.1	1.5+0.1/-0	1.5±0.25	1.75±0.1	7.5±0.1
Dimension No.	Ро	P1	P2	t	W	к
Dimension(mm)	4.0±0.1	12.0±0.1	2.0±0.05	0.4±0.05	16.0±0.3	4.5±0.1



Precautions for Use

1. Soldering Condition

1.1 (A) Maximum Body Case Temperature Profile for evaluation of Reflow Profile



Note:

Preheat

Temperature min (T_{smin}) Temperature max (T_{smax}) Time $(T_{smin} \text{ to } T_{smax})$ (t_s) Average ramp-up rate $(T_{smax} \text{ to } T_p)$

Other

Liquidus Temperature (TL) Time above Liquidus Temperature (t L) Peak Temperature (TP) Time within 5 °C of Actual Peak Temperature: TP - 5°C Ramp- Down Rate from Peak Temperature Time 25°C to peak temperature Reflow times Reference: IPC/JEDEC J-STD-020D

150°C 200°C 60-120 seconds 3°C/second max

217°C 60-100 sec 260°C 30 s 6°C /second max. 8 minutes max. 3 times

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